

**Final!**

Dear IEEE IES Students and Young Professionals (S&YP),

Congratulation! It is a great honor to announce the Awardees of the IES-SYPA competition for the IEEE ETFA 2018.

Important note for the S&YP that applied for the IES-SYPA:

In this year for the **IEEE ETFA'18** we have received **12** applications for the IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE (IES-SYPA). The average weighted score is **7.08**. We would like to announce **3 IES-SYPA** (recognition diploma plus up-to **USD 2000** travel costs reimbursement) recipients (see the table below).

transaction	applicant	manuscript title	all authors
TF-000566	Dr. Xun Ye, Hanyang University, Korea (South), hanyangxun@gmail.com	An AutomationML/OPC UA-based Industry 4.0 Solution for a Manufacturing System	Xun Ye, Seung Ho Hong
TF-000329	Ms. Karila Palma Silva, Federal University of Santa Catarina (UFSC), Brazil, karila@outlook.com	An Empirical Study on the Adequacy of MBPTA for Tasks Executed on a Complex Computer Architecture with Linux	Karila Palma Silva, Luis Fernando Arcaro, Daniel Bristot de Oliveira, Romulo Silva de Oliveira
TF-005975	Mr. Daniel Rivas, Universitat Autònoma de Barcelona, Spain, Daniel.Rivas@uab.cat	Synthesis of Controllers from Finite State Stack Machine Diagrams	Daniel Rivas, Pragna Das, Joaquín Saiz-Alcaine, Lluís Ribas-Xirgo

**Mandatory requirements and important notes:**

- I. **Please take into account that IEEE IES must follow general rules of IEEE related with OFAC Sanctions Programs to learn more please see <https://www.ieee.org/about/compliance/ofac/sanctions.html>. For more details, you may ask The Legal and Compliance Department available to assist with reviewing any questions that you may have with respect to OFAC or other compliance matters and can be reached at [compliance@ieee.org](mailto:compliance@ieee.org).**
- II. **Students and Young Professionals** have to present their project in a 3-minutes speech (3Ms) with hardware demonstration (if applicable) or video clip.
- III. **Please send the declaration and confirmation that you will prepare a 3 minutes movie and speech to **Hani Vahedi** ([hani.vahedi@ieee.org](mailto:hani.vahedi@ieee.org)) and **Marek Jasinski** ([gold.ies.ieee.chair@gmail.com](mailto:gold.ies.ieee.chair@gmail.com)) as fast as possible, but not later than **22.08.2018!****
- IV. **Then, you will receive the full instruction on how to prepare that movie and speech for 3Ms IES-SYPA Speech Video Session.**
- V. Your video will be uploaded on IES YouTube Channel, Facebook Page, and IEEE Collabratec to be available during the conference. Important:
  - a. Please open an **IEEE Collabratec** account with your IEEE login information.
  - b. For the confirmation, please send to [hani.vahedi@ieee.org](mailto:hani.vahedi@ieee.org) your IEEE Collabratec username email.
  - c. You will be added to the IES-SYPA Group.
  - d. Once your video is approved and uploaded to the IES YouTube, then you should post it to the IEEE Collabratec Group and to the Facebook event page.

- VI. Please be sure that during the conference **you will have your video available also off-line** and the hardware demonstration (if applicable).  
***(Time and place for 3Ms presentation will be announced by the General Chair of the Conference)***
- VII. The diplomas for the IES-Student Paper Travel Assistance (IES-SYPA) will be presented during the conference.  
***(Time and place will be announced by the General Chair of the Conference - usually Gala Dinner)***
- VIII. **Take photos during the conference and submit them on your and IES Facebook profile.**
- IX. Submit your expenses report and chose the IES-SYPA payment method (wire transfer or cheque). All documents have to be sent to:  
IES Treasurer **C.J. (Allen) Chen**: [c.j.chen@ieee.org](mailto:c.j.chen@ieee.org)  
with CC to the Chair of the SYP Activity Committee Marek Jasinski: [gold.ies.ieee.chair@gmail.com](mailto:gold.ies.ieee.chair@gmail.com).
- X. PLEASE NOTE THAT IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE is consist of:  
- Recognition Diploma and  
- up to USD **2000** travel cost reimbursements.
- XI. You can find all the necessary information on Industry Electronics Society websites:  
<https://www.facebook.com/IndustrialElectronicsSociety/>  
<http://www.ieee-ies.org/SYP>
- XII. Instruction for travel reimbursements can be found at:  
<http://www.ieee-ies.org/members/treasurer-information>  
Please fill in the following documents:
- Single or Multi-Currency Expense Report Form.
  - Wire Transfer Request Form.
  - Remember to send in pdf your invoices and receipts from, e.g. hotel, airplane, conference fee, taxi, bus, train, meals.

On behalf of the IEEE IES-SYPA Competition Jury:

*IEEE IES President Xinghuo Yu, IES Treasurer C.J. (Allen) Chen, and IES President Elect Terry Martin,  
Vice President for Conference Activities Juan José Rodríguez Andina,  
Vice President for Membership Activities Yousef Ibrahim,  
Conference General Chairs: Luca Durante, Lucia Lo Bello, Roberto Oboe,  
Web & Information Committee: Andres A. Nogueiras Melendez, Aleksander Malinowski,  
Ad-Hoc committee related to IEEE OFAC Sanctions Programs:  
Gus Wagner Director, Technical Activities Operations and Society Support Services IEEE Technical Activities.  
Stephanie Hong, CCEP Compliance Research Analyst Legal and Compliance Department IEEE.  
Matt LaFleur Technical Community Program Coordinator IEEE Technical Activities.  
and Young Professional & Student Activity Committee: Marek Turzynski, Hani Vahedi, Marek Jasinski.*

*Congratulations and Good Luck,  
Chair of the IEEE IES Young Professional & Student Activity Committee,  
Marek Jasinski*